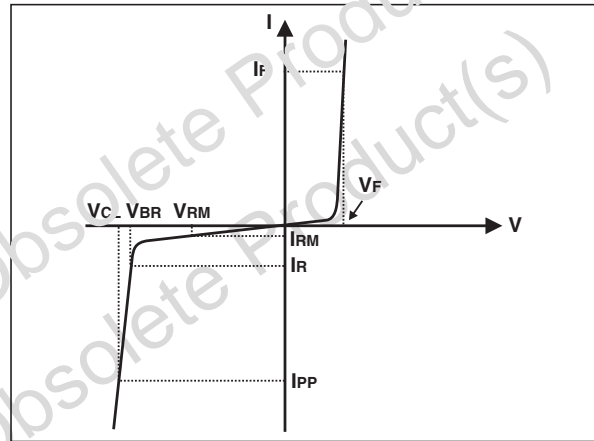


ABSOLUTE RATINGS (limiting values)

Symbol	Parameter and test conditions	Value	Unit
P_R	DC power per resistance	0.1	W
P_T	Total DC power per package	0.6	W
T_j	Maximum junction temperature	125	°C
T_{op}	Operating temperature range	-40 to + 85	°C
T_{stg}	Storage temperature range	125	°C

ELECTRICAL CHARACTERISTICS ($T_{amb} = 25\text{ °C}$)

Symbol	Parameter
V_{BR}	Breakdown voltage
I_{RM}	Leakage current @ V_{RM}
V_{RM}	Stand-off voltage
V_{CL}	Clamping voltage
R_d	Dynamic impedance
I_{PP}	Peak pulse current
$R_{I/O}$	Series resistance between Input and Output
C_{line}	Capacitance per line



Symbol	Test conditions	Min.	Typ.	Max.	Unit
V_{BR}	$I_R = 1\text{ mA}$	5.5	7	9	V
I_{RM}	$V_{RM} = 3.3\text{ V per line}$			500	nA
$R_{I/O}$	$I = 10\text{ mA}$	80	100	120	Ω
C_{line}	$V_R = 2.5\text{ V}, F = 1\text{ MHz}, 30\text{ mV (on filter cells)}$	50	60	70	pF

Fig. 1: S21 (dB) attenuation measurements and Aplac simulation.

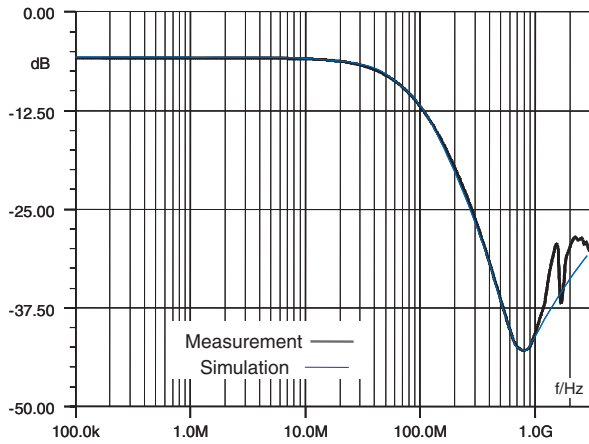


Fig. 2: Analog crosstalk measurements.

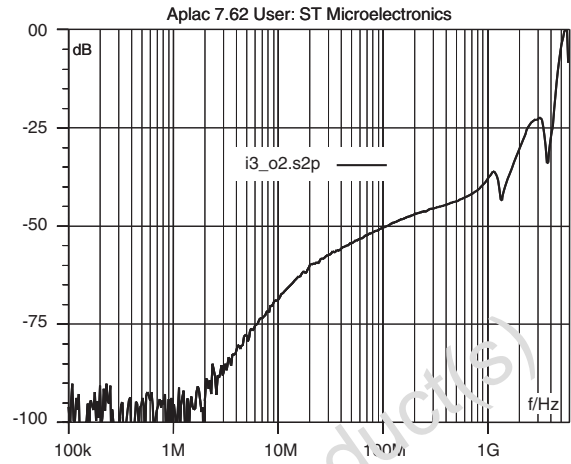


Fig. 3: Digital crosstalk measurements.

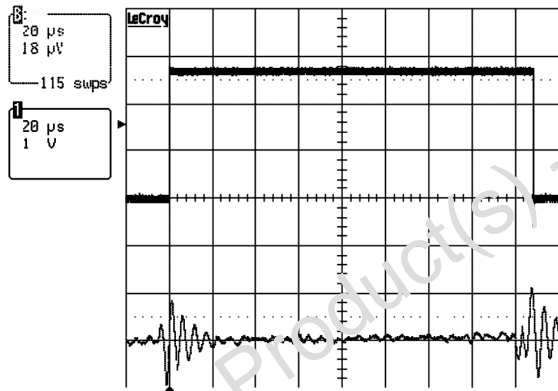


Fig. 4: ESD response to IEC61000-4-2 (+15kV air discharge) on one input V(in) and one output V(out).

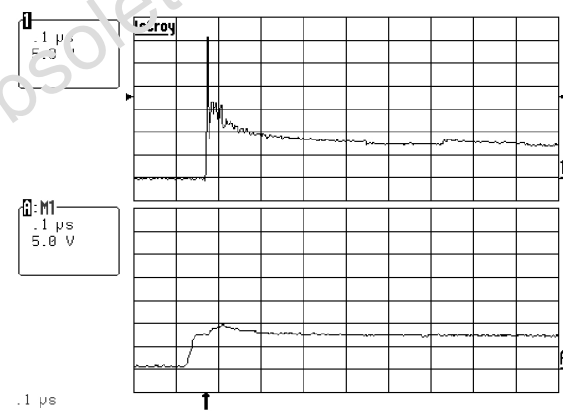


Fig. 5: ESD response to IEC61000-4-2 (-15kV air discharge) on one input V(in) and one output V(out).

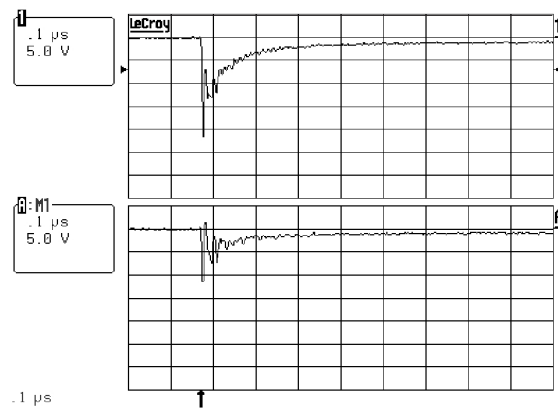
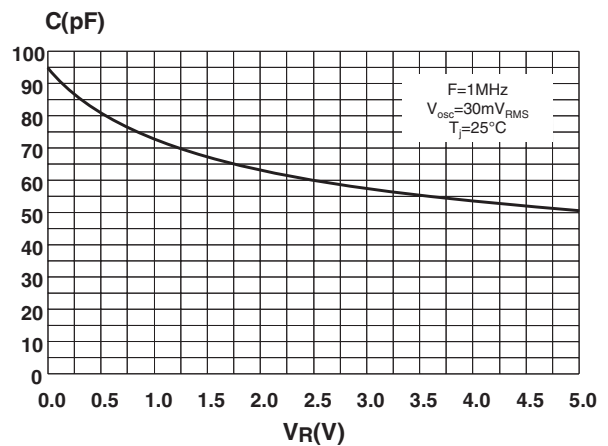
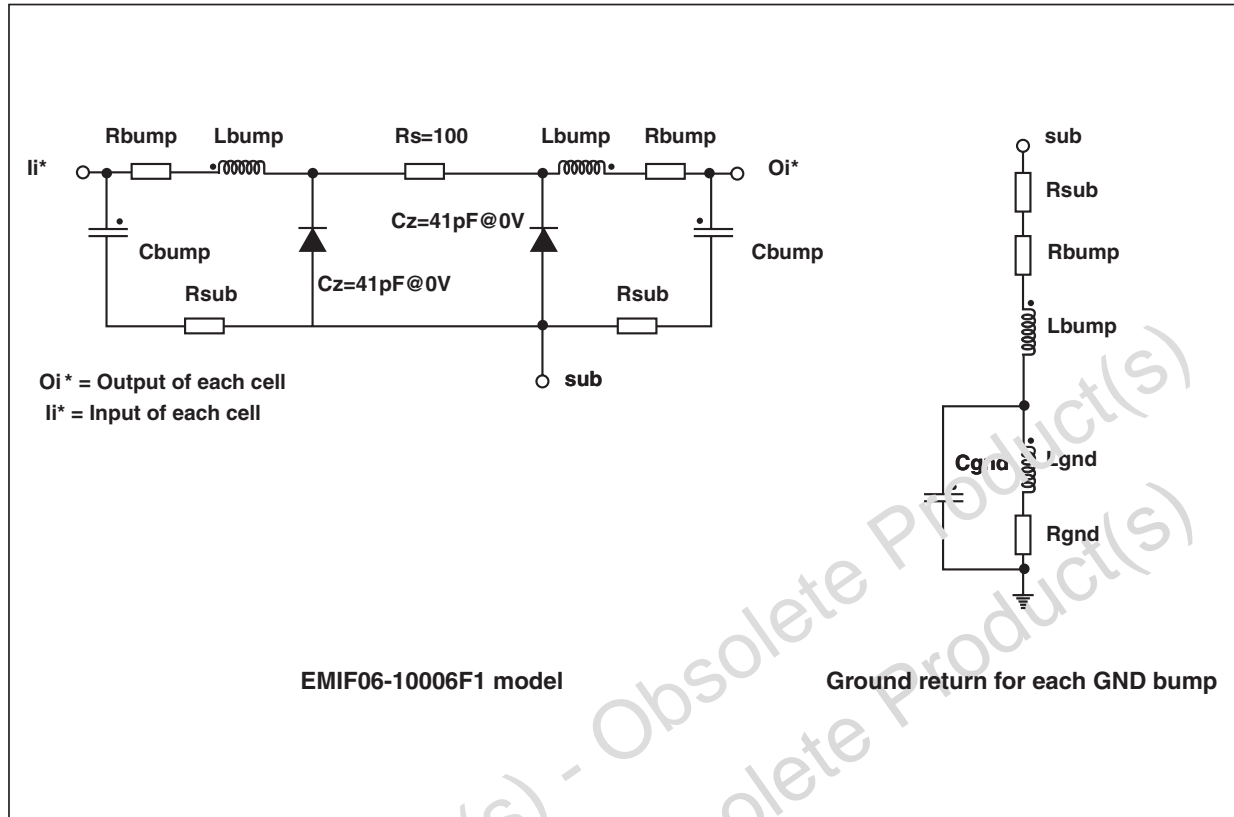


Fig. 6: Line capacitance versus applied voltage for filter.



EMIF06-10006F1

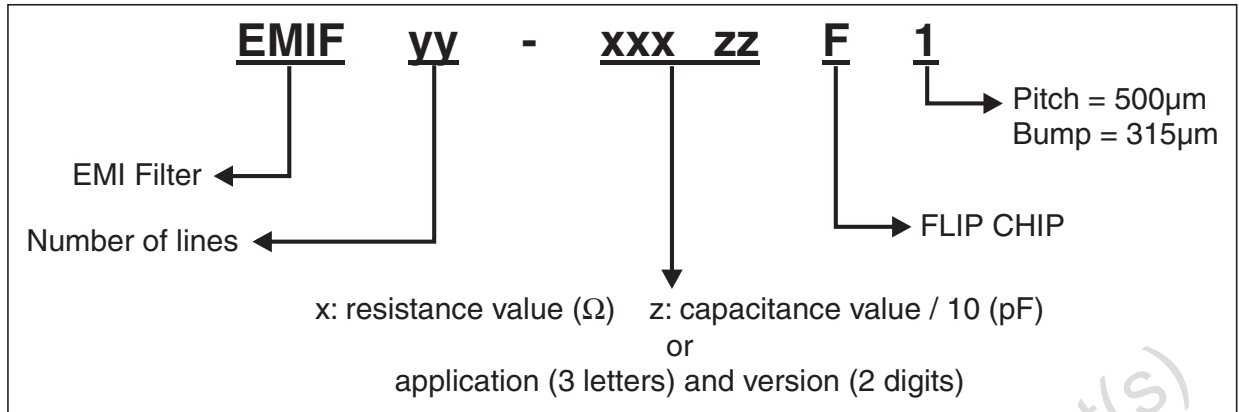
Aplac model



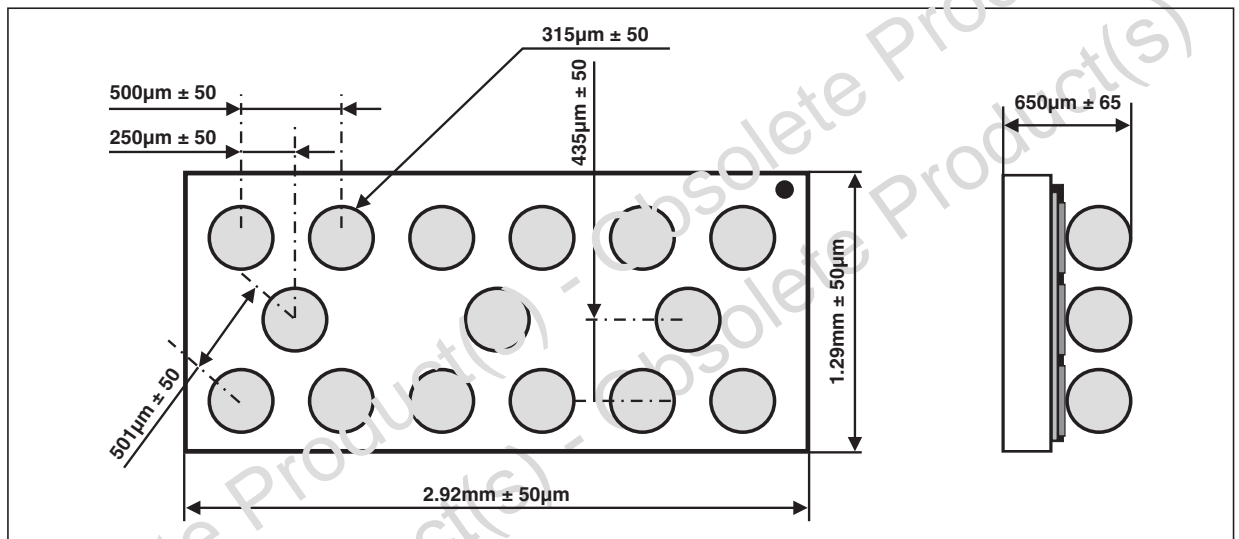
Aplac parameters

aplacvar Rs	100 Ω
aplacvar Cz	41 pF
aplacvar Lbump	50 pH
aplacvar Rbump	20 m
aplacvar Cbump	1.2 pF
aplacvar Rsub	100 m
aplacvar Rgnd	100 m
aplacvar Lgnd	100 pH
aplacvar Cgnd	0.15 pF

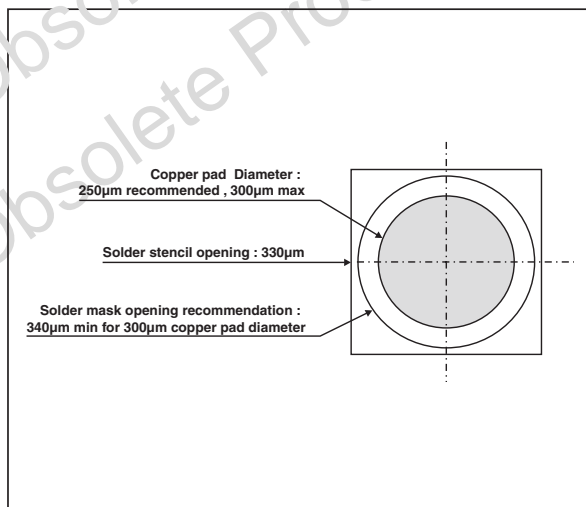
ORDER CODE



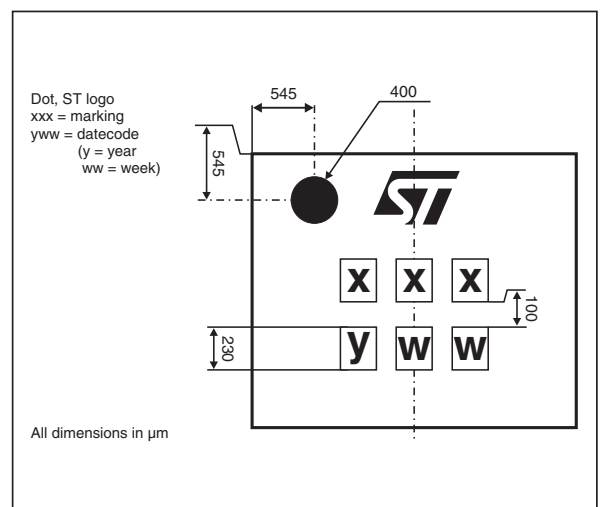
PACKAGE MECHANICAL DATA



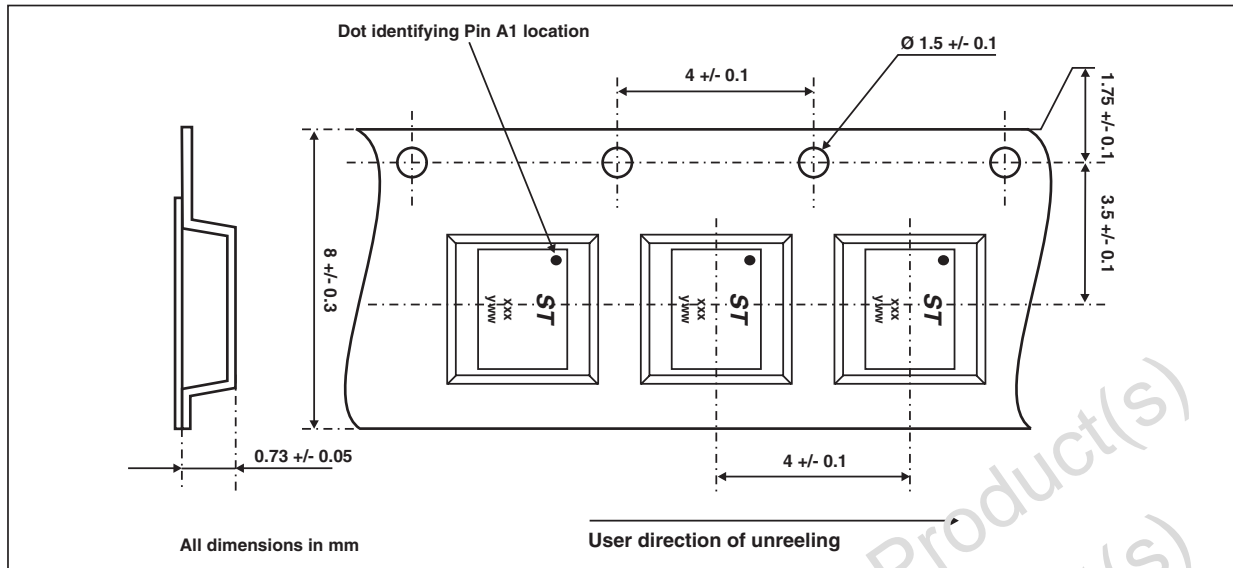
FOOT PRINT RECOMMENDATIONS



MARKING



FLIP-CHIP TAPE AND REEL SPECIFICATION



OTHER INFORMATION

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
EMIF06-10006F1	FTT	Flip-Chip	5.4 mg	5000	Tape & reel

Note: More packing informations are available in the application note AN1235: "Flip-Chip: Package description and recommendations for use"

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